

Application No.: 10/617,727Docket No.: 2336-193

ABSTRACT

~~Disclosed is a~~ A method of manufacturing a light-emitting diode (LED) device, which is advantageous in terms of easy formation of metal material reflective surfaces using a lead frame, thereby improving the luminance characteristics by a simple manufacturing process. ~~The current method includes forming [[the]]~~ a lead frame having a first pattern part mounted with an LED chip, a second pattern part electrically connected to the first pattern part to be used as an electrode, a third pattern part spaced from the first pattern part to be electrically insulated from the first pattern part and used as another electrode, and a fourth pattern part and a fifth pattern part integrated with both sides of the first pattern part, forming a layer plated with a metal having high reflectivity on the fourth and fifth pattern parts, and upwardly folding the fourth and fifth pattern parts to be perpendicular to the first pattern part to form [[the]] reflective surfaces. ~~Accordingly, the reflective surfaces of a surface-mountable LED device, regardless of a mold type or a pre-mold type, can be readily formed from the lead frame with excellent heat releasing performance, whereby the LED device exhibits high heat releasing effects, therefore preventing the deterioration of luminance characteristics.~~